



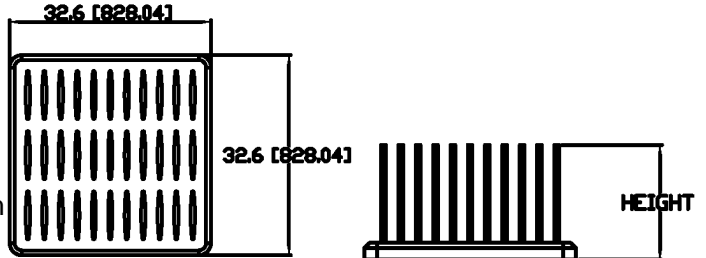
Model : MBA33001 Series



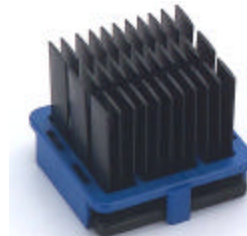
BGA Heat Sink Specification

For 33x33 Chip set

1. Material : Al 6063
2. Dimension :
 Foot print : 33x33mm
 Height : 12,15,18,21,23,28,33 mm
 Base (thickness) : 2.6mm



3. Finish: Black Anodize
4. Chip set package thickness and clip color
 3.3+/-0.25mm - Yellow clip
 1.7+/-0.25mm - Blue clip
 0.8+/-0.25mm - Orange clip
5. Accessory :
 Clip : Plastic (UL94-V0)
 Thermal pad : T710 or others



Performance

Heat Source (LxW)	15x15
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